

Neotech AMT

Advanced Manufacturing Technologies for 3D Printed Electronics

Scalable 3D Printed Electronics – From Fully Additive to High Volume Manufacture.

Dr. Martin Hedges – Managing Director

14.11.2018 - IDTechEX Printed Electronics USA

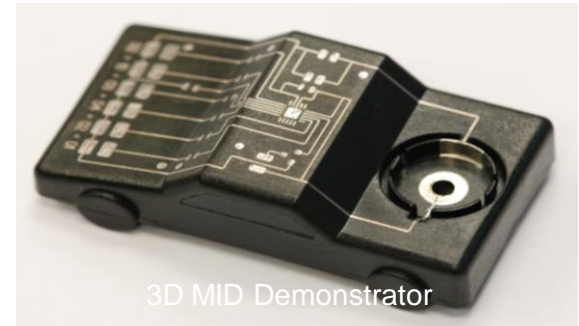
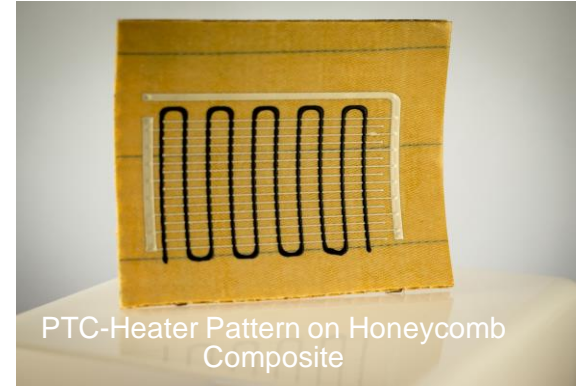


Agenda

- 1. Company Overview*
- 2. Designing a 3D Printed Electronics Process*
- 3. Application Examples*
- 4. Beyond Simple Circuits*
- 5. 3D Print Systems*

Neotech AMT GmbH

- Neotech manufactures system for 3D Printed Electronics.
- Pioneering 3D PE development since 2009.
- First 3D capable system installed in 2010.
- First mass-production capable system of type 45X built 2012.
EU/US/CN patent granted 2015.
- 1st commercial sale & install of mass production system in Q3 2013.
- 1st commercial mass production started on Neotech systems in Q3 2015.



Market Need for 3D Printed Electronics

Design Flexibility

Integration of Mechanics-
Electronics-Optics

Flexibility of Shape

Minaturisation

New Functionality

Economics

Reduced Part Count

Shorter Process Chains

Reduced Materials Use

Increased Reliability

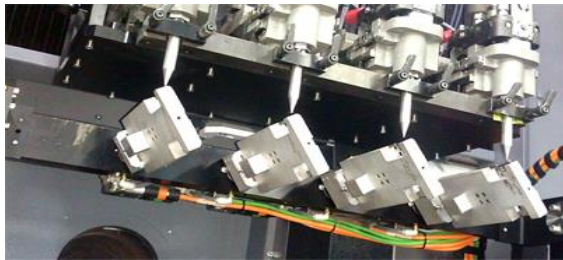
Environmental

Reduced Materials Mix

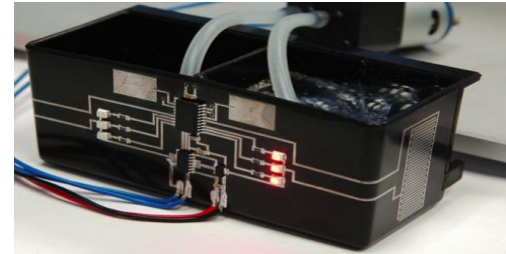
Simplified Recycling &
Disposal

Reduced Material Quantity

Reduced Parts Tourism



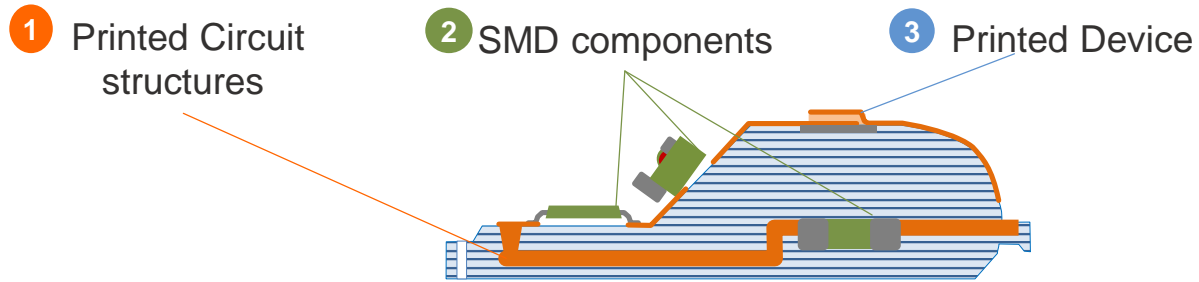
Multi-station Printing
at LITE-ON Mobile Mechanical SBG



Tank Filling Sensor
Automotive

Methods for 3D Printed Electronics (3D PE)

How to add electronic functionality to 3D shaped parts?

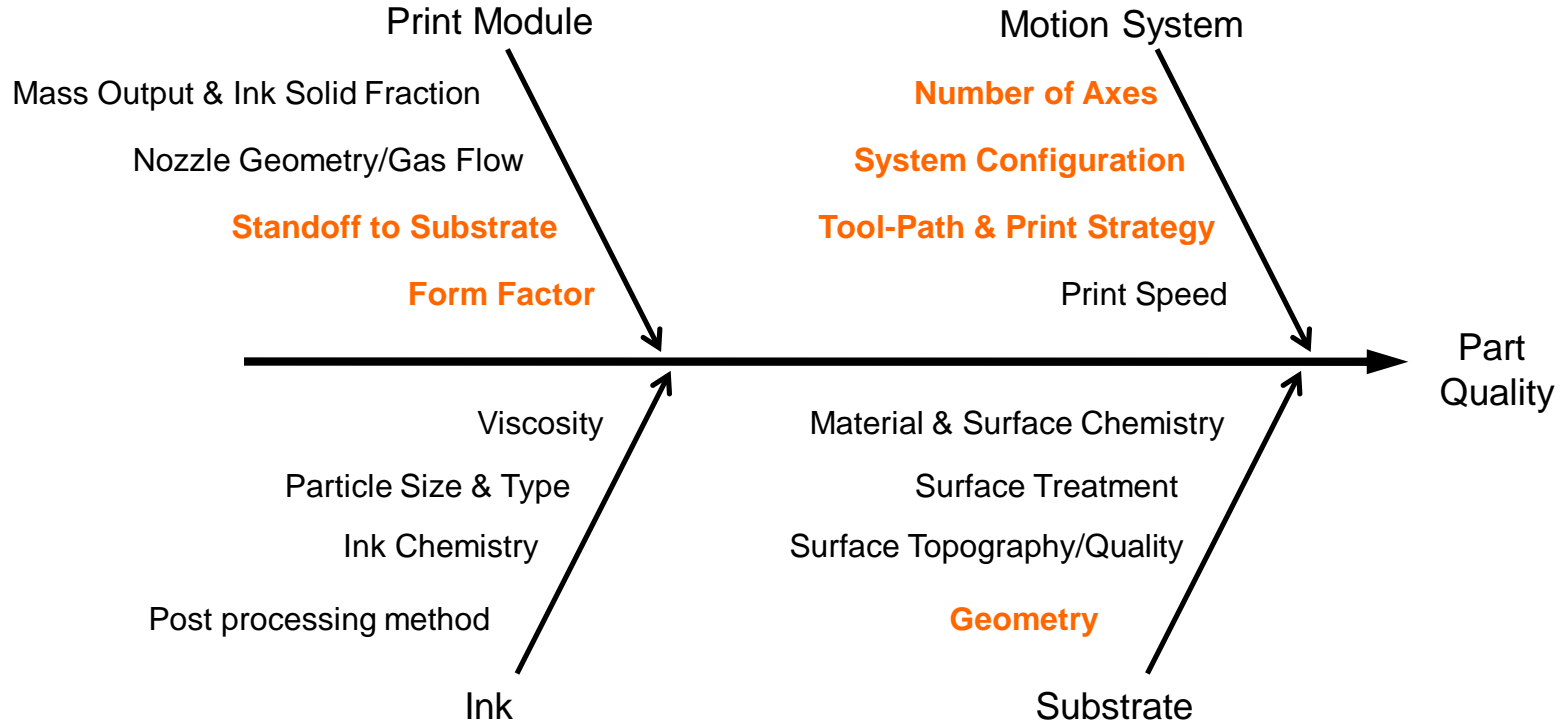


*Method 1: Print on conventionally manufactured 3D parts: moulded, machined, composite
Development started 2010*

*Method 2: Print on/in part manufactured layer-by-layer process: FDM, SLS, SLA, etc:
Development started 2016*

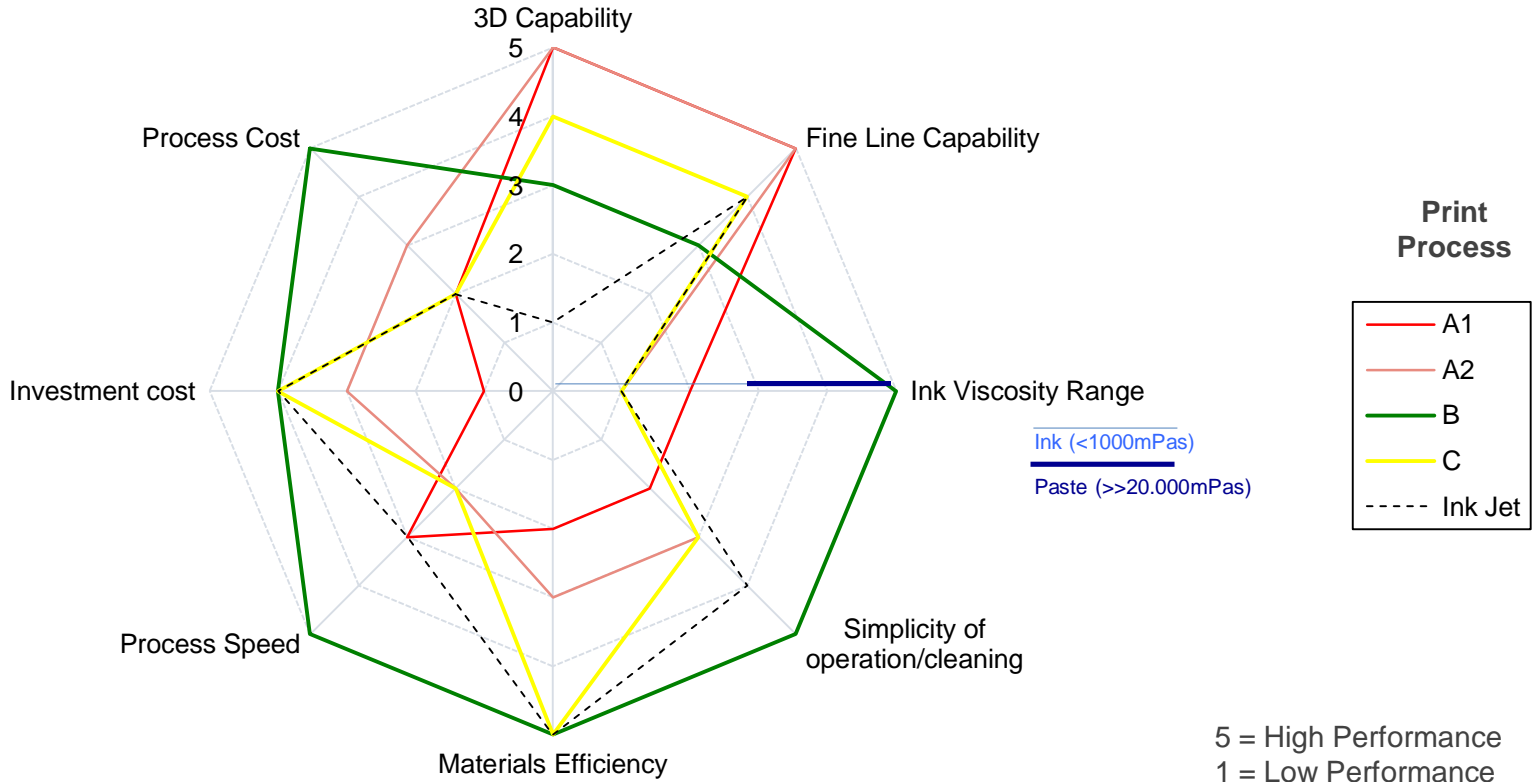
Enabling a 3D Printing Process

Key Process Variables



Print Head Selection

Each print process has a unique combination of characteristics
Process selection driven by application requirements:



Motion 3D CAD/CAM

CAD/CAM package that seamlessly interacts with the print platform to enable the printing of highly complex 3D circuits:

Simple process flow, 3+2 indexed to 5 axis simultaneous printing

Optimised cycle times via free definition of the print sequence

Printing path & machine motion simulation

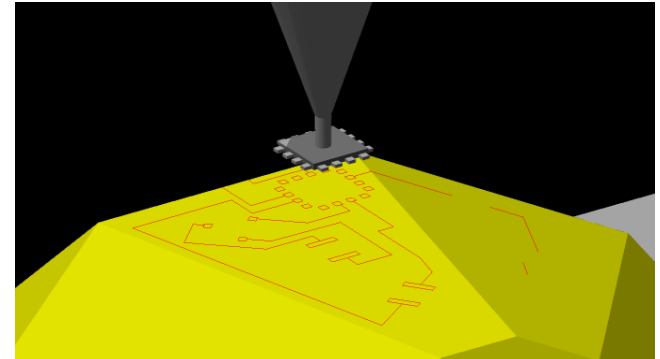
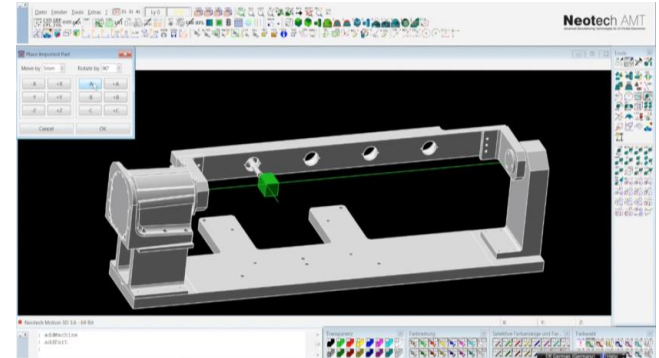
Collision detection

Look ahead function for accurate start/stops of the print process

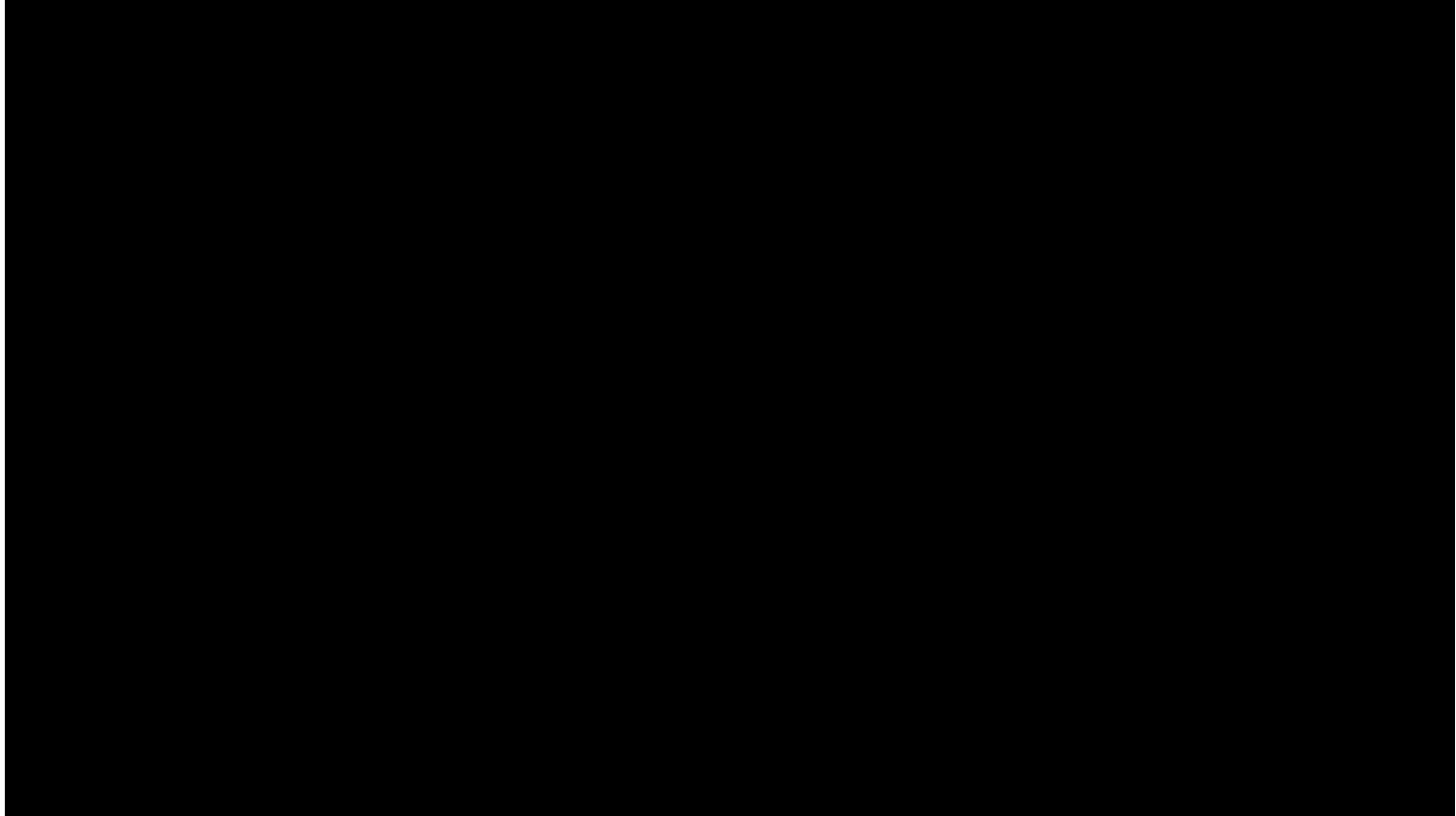
CAM Check Function – check programmed tool-path vs. machine process limits (point to point time, acceleration and axis speed)

Machine specific ISO Standard G-Code post processor

All process steps (3D Print, 3D Circuit Print, SMD Pick & Place, Pre-/Post-processing) in single machine code



5 Axis Print Demonstration



Example of Dual Print Technologies



NanoJet

Fine Line (ca. 60um)
Ag Nano-particle Ink
Viscosity: 20mPas

PiezoJet

Medium Line (300um)
Ag Ink with particles D90 ca. 6um
Viscosity ca. 70.000mPas



Current Applications

Printed Antenna/Circuits

1. Current Process Route: Printing Ag inks on filled PA resins and oven sinter
 2. Low temperature inks for PC/ABS
 3. RF Performance: matches industry standard
-
1. Production Costs: specific antenna designs show cost reduction of compared to current manufacturing techniques



Demonstration Antenna
Courtesy: LITE-ON Mobile Mechanical SBG



Multi-station Printing.
Courtesy: LITE-ON Mobile Mechanical SBG

Switch Paddle Circuit

Automotive

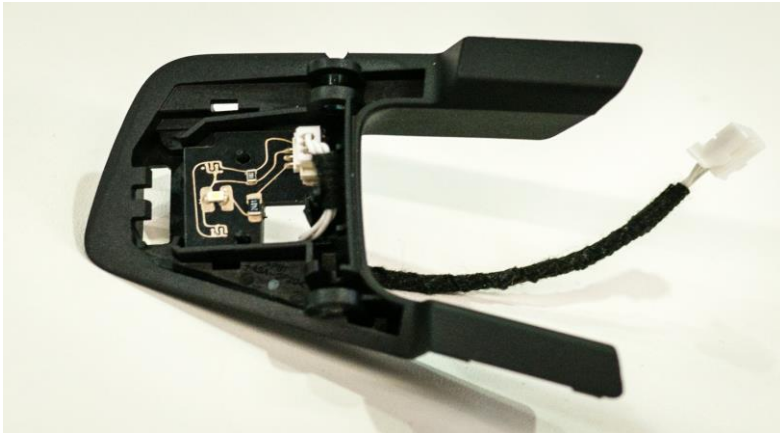
Proof of Concept study

Target higher level of integration & cost saving

Circuit printed directly on switch paddle body – remove PCB

Next step replace connector cable with printed circuit/interconnect – cost saving

Courtesy:



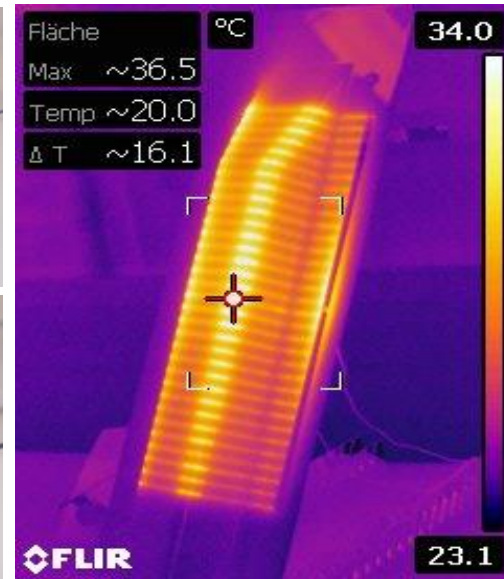
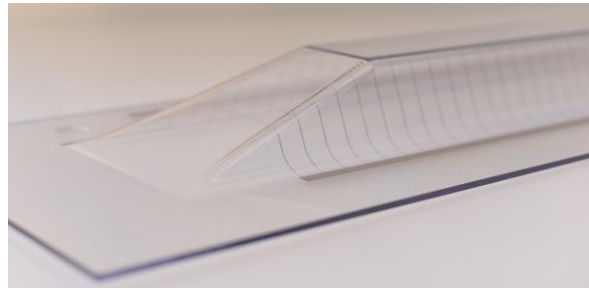
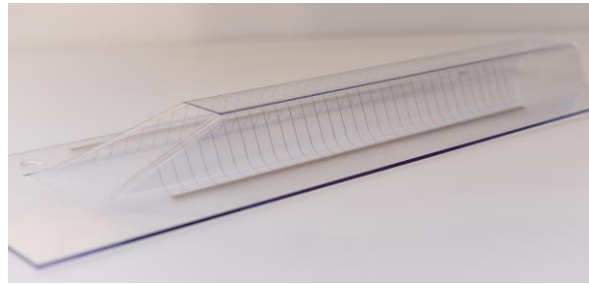
3D Heater Patterns on PC

Automotive Glazing

Ag heater circuits printed on large PC part: 750 x 250 x 170mm (x-y-z)

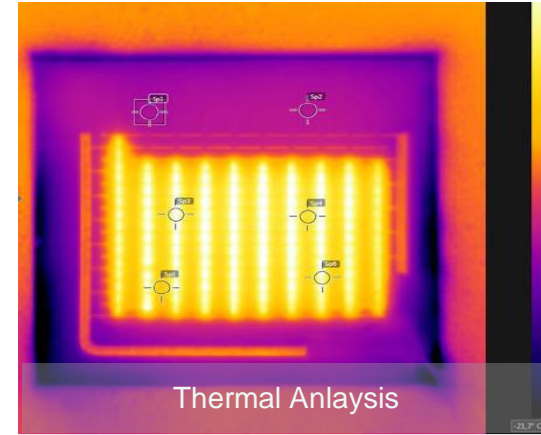
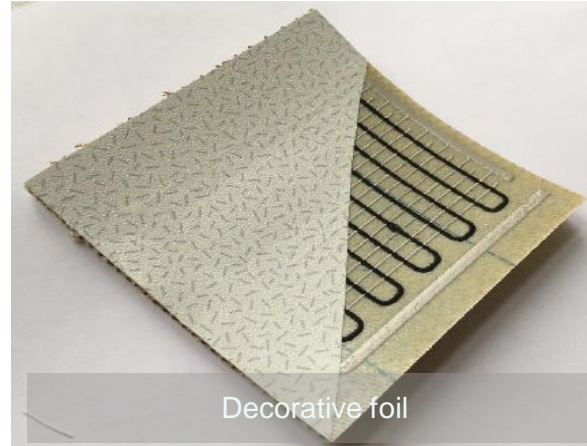
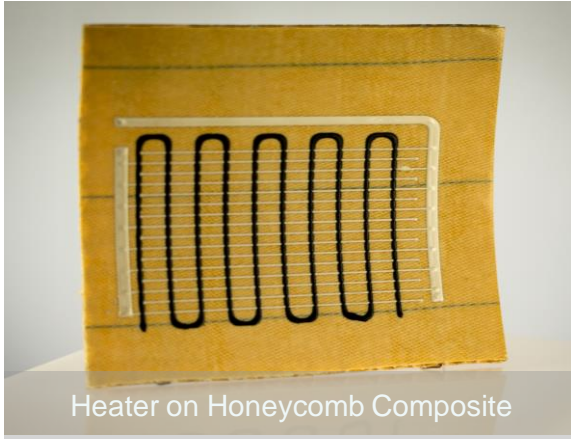
Heating 18W (3A/9V) – tune print process to increase heating capacity

Parts to be coated with protective anti-scratch/anti-UV layer



3D Heater Patterns on Honeycomb Composite

Aerospace – Cabin Interior

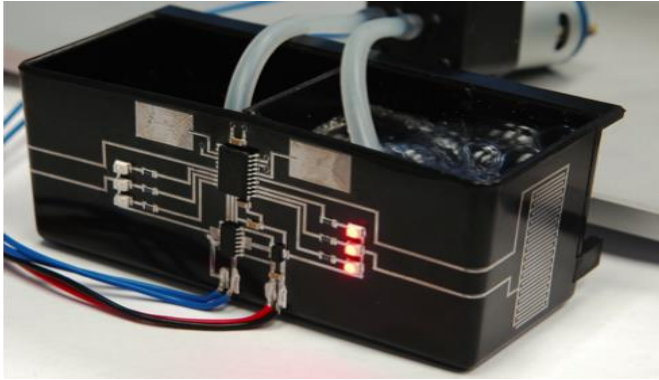


Ag circuit with PTC resistive heater: light weight, safe & integrated into cabin side wall.

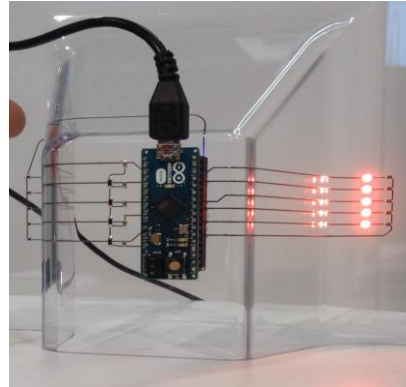
Rear side cooled to under -20°C

Heater at 38°C

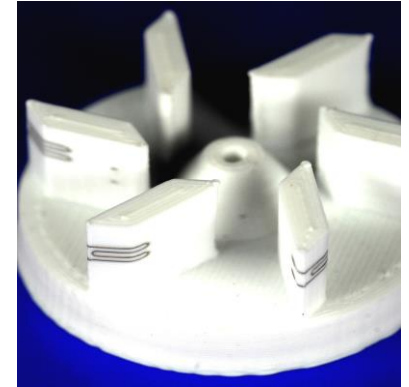
3D Printed Sensors



Tank Filling Sensor
(Capacitive)



Touch Sensor on
moulded PC
(Capacitive)



Strain Gauge on 3D
Printed PLA
(Fraunhofer IFAM)

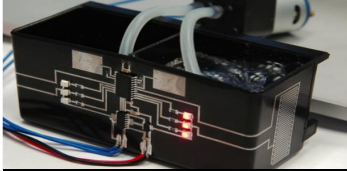
Beyond Simple Circuits?

Is it possible to add extra functionality to produce more sophisticated 3D Printed Electronics?

<i>Component</i>	<i>Function</i>
Conductors	Carry Current
Antenna	Broadcast/Receive
Sensors	Input
Heater	Heat Part
Resistors	Control Current Flow
Capacitors	Filter, Charge Storage
Inductors	Filter, Transform/Transfer
Diodes	Valve
Transistors	Amplify, Switch
Memory	Information Storage
Emitters	Display Output
Power Source	Energise Circuit

Additional Functionality for 3D Printed Electronics

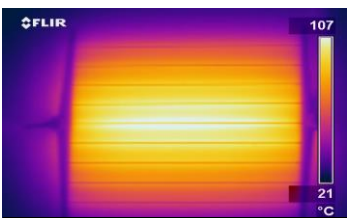
3D Today



Circuits & Sensors

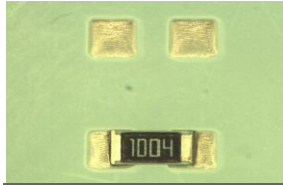


Antenna

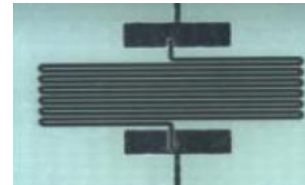


Heater Patterns

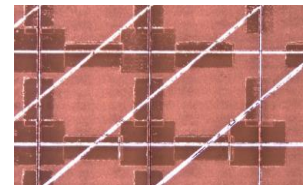
Printed in 2 to 2½D Today - 3D Future?



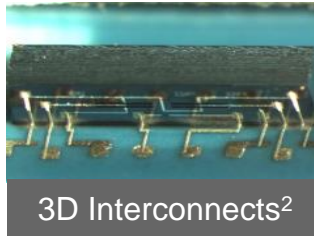
Chip Bonding¹



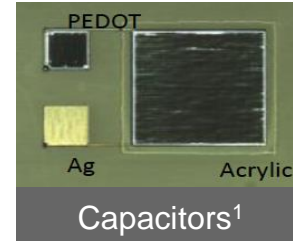
Resistors¹



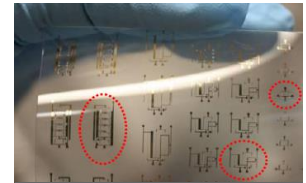
Multilayer Circuits¹



3D Interconnects²



Capacitors¹



Transistor Circuits¹

¹ Courtesy Optomec Inc.

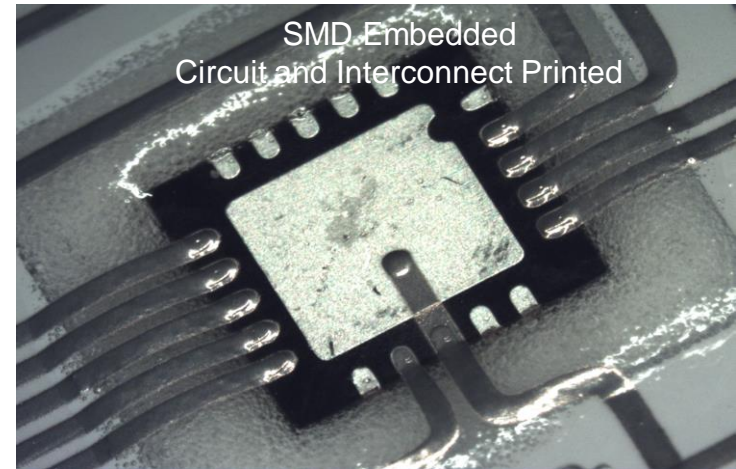
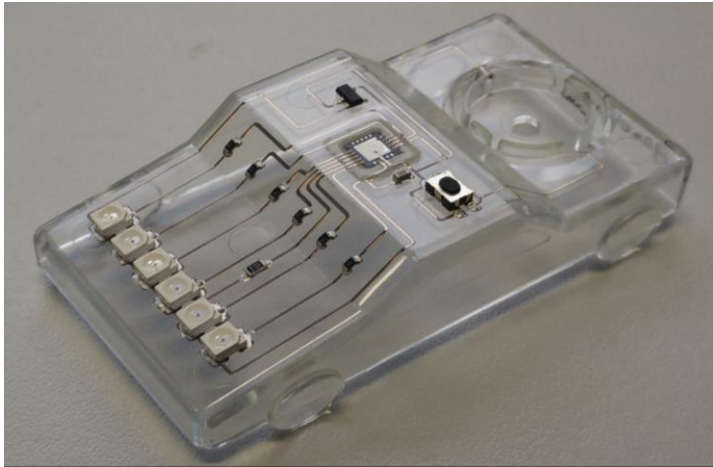
² Courtesy Fraunhofer IKTS

Embedding SMDs

QFN (Quad Flat No-lead) Microcontroller

Contact Pads 230 μ m

Fixed with 2 Component Epoxy

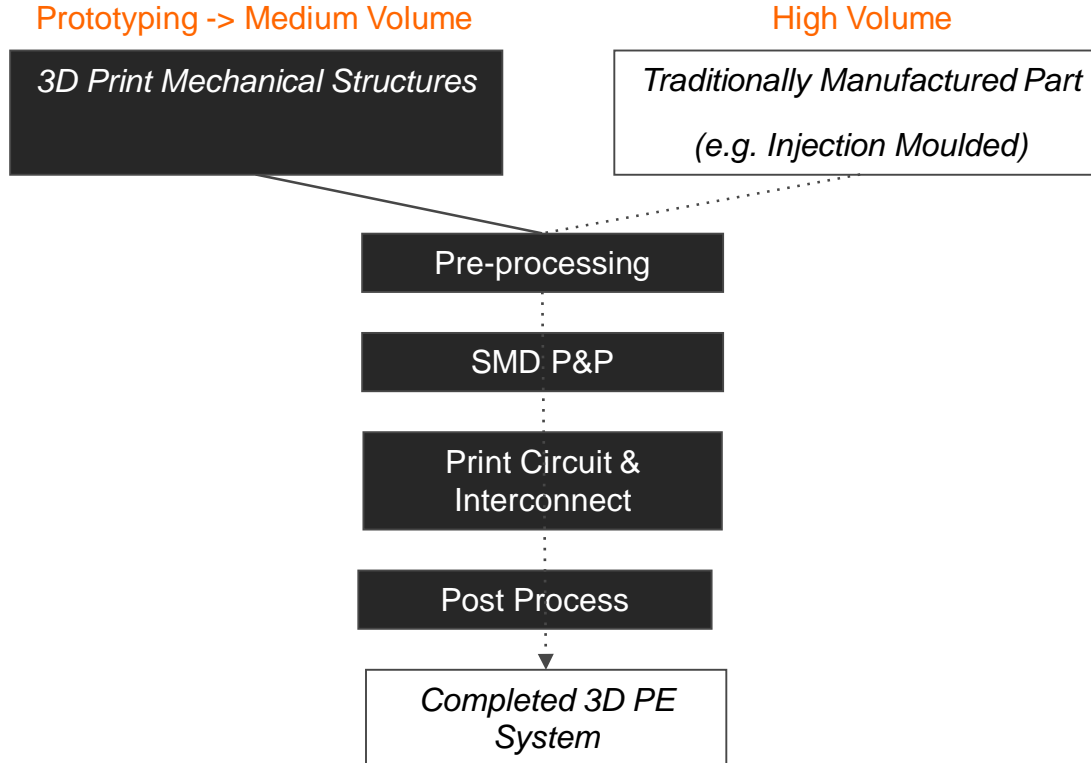


Project in cooperation with:



Technology Goal

To provide complete 3D Digital Manufacturing Process Chains spanning all production levels

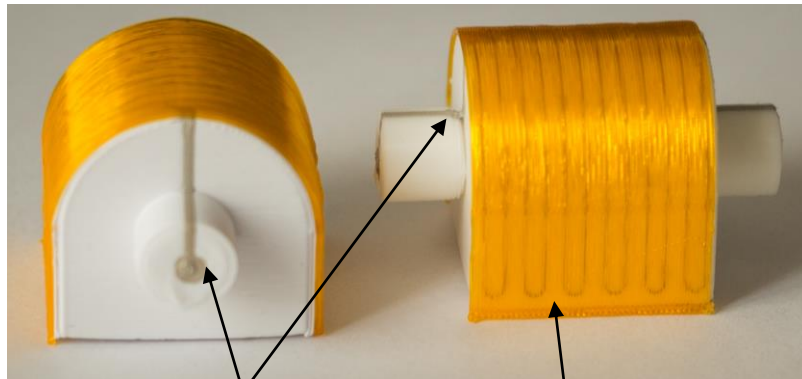
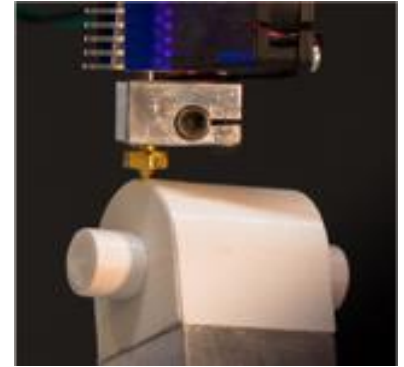


“Fully Additive” 3D Printed Electronics

Combine electronics build of structural elements:
Fused Deposition Modelling (thermoplastics) & Dispensing (resins)

Single CAD/CAM interface for all processes in 5 axis:

1. Structural build
2. SMD pick & place
3. Circuit Printing and interconnecting SMDs
4. Pre- & Post-processing



Ag bus bars

Ag heater pattern



Thermal Image at 60°C

EU PENTA Project: Hyb-Man

Hybrid 3D Manufacturing of Smart Systems

1. Develop hybrid 3D manufacturing methods to enable flexible first time right production of smart systems
2. 3D Printing of polymers in combination with 3D Printed Electronics as core production technologies
3. In-line testing and quality monitoring processes will be integrated as part of the complete process chain
4. Outcome: improved Additive Manufacturing processes, a hybrid manufacturing production cell and prototypes of integrated electronic products (LED luminaires, automotive adaptive sensors)

Processes, Materials & Equipment

Industrialization

Products



TNO

Technolution

TU/e
HTSC

reden
research development nederland



Signify



Fraunhofer

Henkel

XENON

Neotech AMT
Advanced Manufacturing Technologies for 3D Printed Electronics



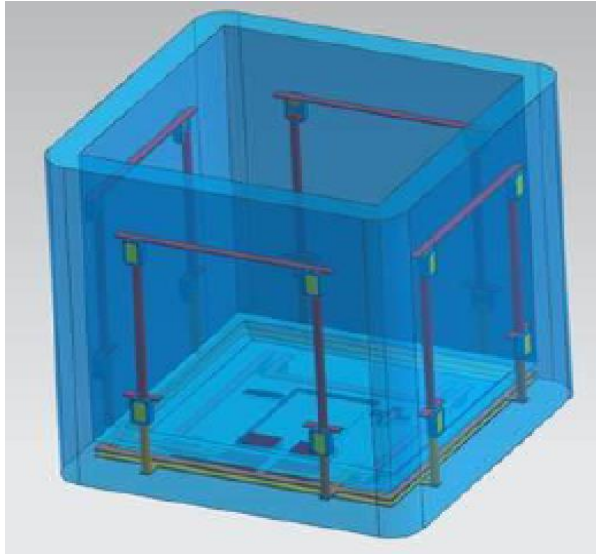
BOSCH

EU PENTA Project: Hyb-Man

First Product Demonstrator: LED Box

20 LEDs added (5 sets of 4):
4 embedded in base, circuit printed to directly contact.
16 LEDs in walls mounted with conductive adhesive.

Side wall circuits use 5 axis motion



EU Manunet Project: AMPECS



1. Will develop fully Additive Manufacturing process for 3D Printing Electronics with Ceramic Substrates
2. The German-Spanish consortium will develop 3D printable ceramic materials for creating the structural body and integrate printed electronics into and onto this component.
3. End use applications will cover areas where harsh environments exists such as automotive and aerospace as well as in mobile communications.



Francesco Alberto S.A.U

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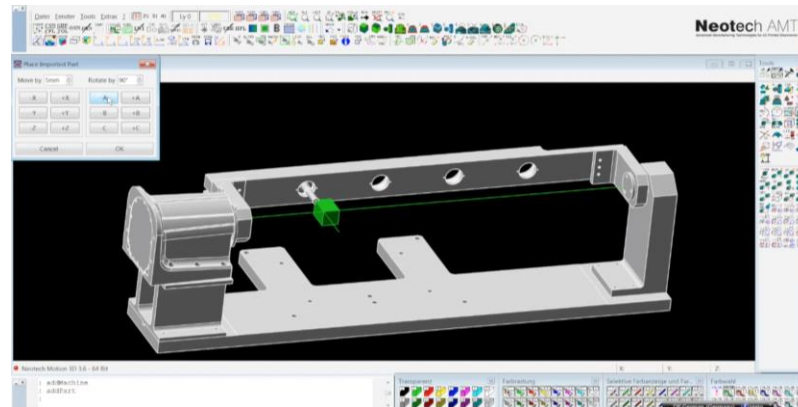
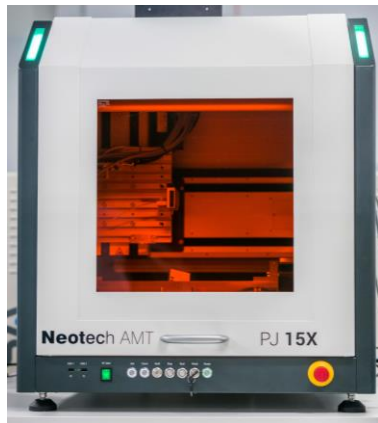


System Offerings

Neotech Products

5 axis machine tools with 3D capable print, pre- and post-processing tools, software, training & service:

Print Platforms	Print/Functionalising Tools	Pre/Post-Processing
45X – Volume Manufacture	Piezo Jetting	CNC Machining
15X – R&D/Product Development	Aerosol Based	Plasma Cleaning
Custom Platforms	Ink Jetting	Sintering (Light/Laser)
CAD/CAM	Dispensing	UV Curing
Motion 3D	FDM	Adaptive Tool Path Vision System
	SMD Pick & Place	





Summary

1. Designing 3D Printed Electronics process
2. Current Application Examples
3. Scalable Process Routes
4. Modular Systems

Neotech AMT

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Thank you for your attention!

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